

## **Quarterly Reliability Monitoring Results**

## Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PESD3V3L1BA-Q Part Description											
									Nexperia DHAM	Protection			
									SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects							
			TEST										
			Pre- and Post-Stress										
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below							
		JESD22-A113 Bake Tamb = 125 °C	24 hours										
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours										
# A1	Preconditioning	Reflow soldering	3 cycles	438	24630	0							
	HTRB	MIL-STD-750-1 M1038 Method A											
# B1	Bias	Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	166	10040	0							
# DI	5.05	. evelue vellage	1000 110013	100	10040	0							
	тс	JESD22-A104											
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	131	7760	0							
	UHAST	JESD22-A118											
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	131	7760	0							
	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 %											
# A3 alt	Autociave	Pressure = 205 kPa (29.7 psia)											
	<b>H3TRB</b> High Humidity High	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of											
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	131	7760	0							
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ =											
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.							
# 60	RSH Resistance to Solder Heat	JESD22-A111	10 -	45	1250	0							
# C8	SD	200 -C = 3 -C	10 s	45	1350	0							
# C10	Solderability	J-STD-002		111	1110	0							

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

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